CLAIMS:

1. A molding apparatus for an electronic device, comprising:

a first mold chase, a second mold chase and a middle plate which is configured to be clamped together with the electronic device between the first mold chase and second mold chase during molding;

a molding cavity formed in the middle plate for receiving molding compound; and

a package pin mounted on the middle plate and movable with the middle plate, a portion of the package pin being positioned to protrude into the molding cavity to form a mark in the molding compound when molding compound is molded around the said portion of the package pin.

2. The molding apparatus as claimed in claim 1, further comprising a fixer mounted on the middle plate, wherein the fixer includes a head portion abutting the package pin which is operative to secure the package pin to the middle plate.

3. The molding apparatus as claimed in claim 2, wherein the fixer comprises a fixing screw having a threaded stem portion for mounting the fixer and a flat head portion configured to abut an end of the package pin.

4. The molding apparatus as claimed in claim 3, wherein the flat head portion covers a top of the package pin.

5. A method of molding an electronic device, comprising the steps of:

positioning the electronic device between a middle plate and a first mold chase of a molding apparatus;

clamping the electronic device and middle plate between the first mold chase and a second mold chase;

introducing molding compound into a molding cavity located in the middle plate, wherein the molding compound is molded around a portion of a package pin mounted on the middle plate which partially protrudes into the molding cavity;

separating the second mold chase from the middle plate to remove cull while the package pin is fixedly secured to the middle plate;

closing the second mold chase onto the middle plate; and thereafter

separating the second mold chase and middle plate from the first mold chase, and removing the electronic device which has been molded.

6. The method of molding an electronic device as claimed in claim 5, wherein the package pin is secured to the middle plate by a fixer mounted on the middle plate, the fixer including a head portion abutting the package pin.

7. A molding apparatus for an electronic device, comprising:

a first mold chase, a second mold chase and a middle plate including a molding cavity which is configured to be clamped between the first mold chase and second mold chase during molding;

at least one ejection pin extending from the first mold chase towards the bottom mold chase;

at least one receiving hole in the middle plate which is sized to allow the ejection pin to pass through the middle plate to contact a molded electronic device positioned on the second mold chase; and

a holding bush located at a base of the first mold chase through which the ejection pin is configured to pass;

wherein the holding bush is at least partially insertable into the receiving hole for guiding the ejection pin precisely into the receiving hole.

8. The molding apparatus as claimed in claim 7, wherein the first mold chase further comprises a runner plate next to the first mold chase which contains runners for channeling molding compound through the runners to the molding cavity, and wherein the holding bush is incorporated into the runner plate.

9. The molding apparatus as claimed in claim 8, wherein a part of the holding bush protrudes from the runner plate to be at least partially insertable into the receiving hole.

10. The molding apparatus as claimed in claim 9, wherein the part of the holding bush protruding from the runner plate is substantially frustoconically-shaped.

CLAIMS:

1. A molding apparatus configured to encapsulate an electronic device in a molding compound to form a molded semiconductor package, the molding apparatus comprising:

a first mold chase, a second mold chase and a middle plate which are configured to be clamped together with the electronic device, the middle plate being arranged between the first mold chase and second mold chase during molding;

a molding cavity wholly defined by a cavity formed on one side of the middle plate for receiving molding compound; and

a package pin mounted onto the middle plate and movable with the middle plate relative to both the first and second mold chases during a molding process, a portion of the package pin being positioned to protrude into the molding cavity to form a mark in the molding compound when molding compound is molded around the said portion of the package pin.

2. The molding apparatus as claimed in claim 1, further comprising a fixer mounted on the middle plate, wherein the fixer includes a head portion abutting against a head portion of the package pin to secure the package pin to the middle plate.

3. The molding apparatus as claimed in claim 2, wherein the fixer comprises a fixing screw having a threaded stem portion for mounting the fixer to the middle plate.

4. The molding apparatus as claimed in claim 3, wherein the head portion of the fixer covers a head portion of the package pin.